

PW018N10BS7

Perfect MOS5 N-MOSFET 100V, 1.4mΩ, 275A



重庆平伟实业股份有限公司

Features

- Uses PingWei advanced PerfectMOS5 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \times R_{DS(on)}$ product(FOM)
- Excellent Low Ciss
- Qualified according to JEDEC criteria

Benefits

- High robustness and reliability
- Increases maximum current capability
- Low power loss, high power density
- Easy paralleling

Applications

- Synchronous Rectification for AC/DC Quick Charger
- Battery management
- UPS (Uninterruptible Power Supplies)

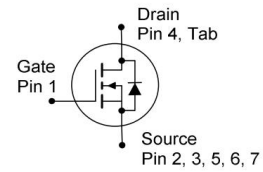
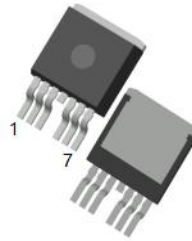


100% DVDS Tested
100% Avalanche Tested

Product Summary

V_{DS}	100V
$R_{DS(on)@10V}$ typ	1.4mΩ
I_D	275A

TO-263-7L



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
PW018N10BS7	PW018N10BS7	TO-263-7L	Tape&Reel	13 inches	24mm	800pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	100	V
Continuous drain current	I_D	330	A
$T_C = 25^\circ\text{C}$ (Silicon limit)		275	
$T_C = 25^\circ\text{C}$ (Package limit)		209	
$T_C = 100^\circ\text{C}$ (Silicon limit)		27	
$T_a = 25^\circ\text{C}$			
Pulsed drain current ($T_C = 25^\circ\text{C}$, $t_p = 100\mu\text{s}$)	$I_{D\ pulse}$	1100	A
Avalanche energy, single pulse ($L=0.5\text{mH}$, $V_{ds}=50\text{V}$)	E_{AS}	484	mJ
Gate-Source voltage	V_{GS}	± 20	V
Power dissipation	P_{tot}	313	W
$T_C = 25^\circ\text{C}$		2.0	
$T_a = 25^\circ\text{C}$			
Operating junction and storage temperature	T_j, T_{stg}	-55...+150	$^\circ\text{C}$
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	T_{sold}	260	$^\circ\text{C}$



Thermal Resistance

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	RthJC	-	0.25	0.40	°C/W	-
Thermal resistance, junction - ambient(min. footprint)	RthJA	-	-	62	°C/W	-

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	100	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{GS(th)}$	2.5	-	3.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}	-	0.08	1	μA	$V_{DS}=100V, V_{GS}=0V$ $T_j=25^\circ C$ $T_j=150^\circ C$
Gate-source leakage current	I_{GSS}	-	± 10	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	1.4	1.8	mΩ	$V_{GS}=10V, I_D=50A$
Transconductance	g_{fs}	-	122	-	S	$V_{DS}=5V, I_D=50A$

Dynamic Characteristic

Input Capacitance	C_{iss}	-	9831	-	pF	$V_{GS}=0V, V_{DS}=50V,$ $f=1MHz$
Output Capacitance	C_{oss}	-	3858	-		
Reverse Transfer Capacitance	C_{rss}	-	127	-		
Gate Total Charge	Q_G	-	166	-	nC	$V_{DS}=50V, I_D=100A,$ $V_{GS}=10V$
Gate-Source charge	Q_{gs}	-	55	-		
Gate-Drain charge	Q_{gd}	-	44	-		
Turn-on delay time	$t_{d(on)}$	-	27	-	ns	$V_{GS}=10V, V_{DD}=50V,$ $R_{G_ext}=1.6\Omega, I_D=100A$
Rise time	t_r	-	99	-		
Turn-off delay time	$t_{d(off)}$	-	51	-		
Fall time	t_f	-	118	-		
Gate resistance	R_G	-	1.0	-	Ω	$V_{GS}=0V, V_{DS}=0V,$ $f=1MHz$



Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	0.82	1.2	V	$V_{GS}=0V, I_{SD}=50A$
Body Diode Continuous Forward Current	I_S	-	-	275	A	$TC = 25^{\circ}C$
Body Diode Pulsed Current	I_S pulse	-	-	1100	A	$TC = 25^{\circ}C$
Body Diode Reverse Recovery Time	t_{rr}	-	101	-	ns	$V_R=50V, I_F=50A,$ $diF/dt=100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{rr}	-	194	-	nC	



Typical Performance Characteristics

Fig 1: Output Characteristics

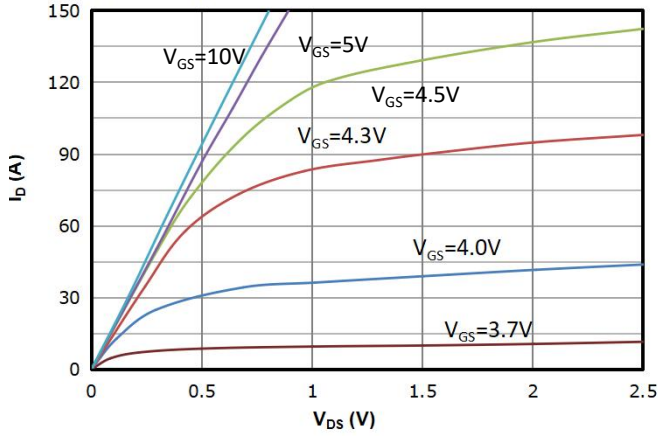


Fig 2: Transfer Characteristics

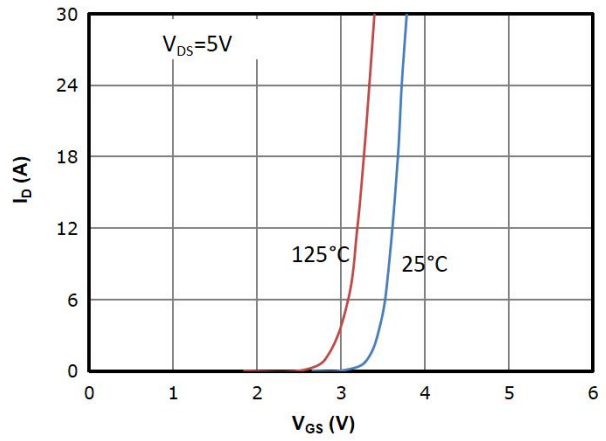


Fig 3: $R_{DS(on)}$ vs Drain Current and Gate Voltage

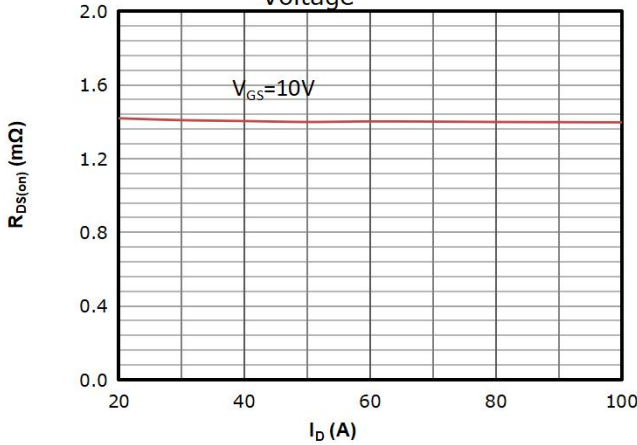


Fig 4: $R_{DS(on)}$ vs Gate Voltage

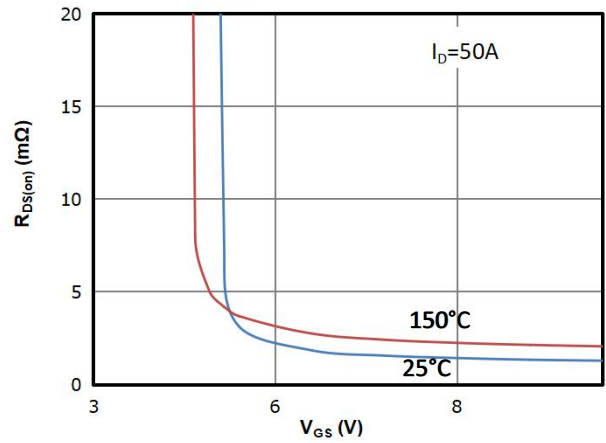


Fig 5: $R_{DS(on)}$ vs. Temperature

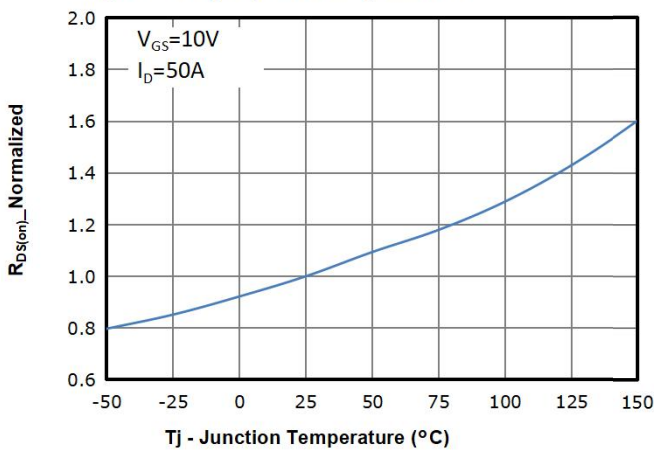


Fig 6: $V_{GS(th)}$ vs. Temperature

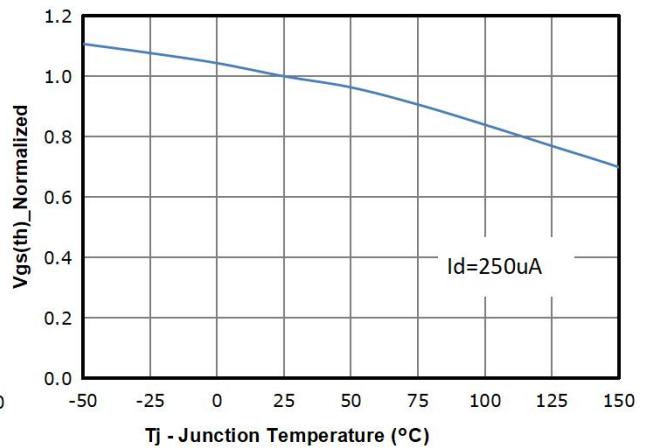




Fig 7: BVdss vs. Temperature

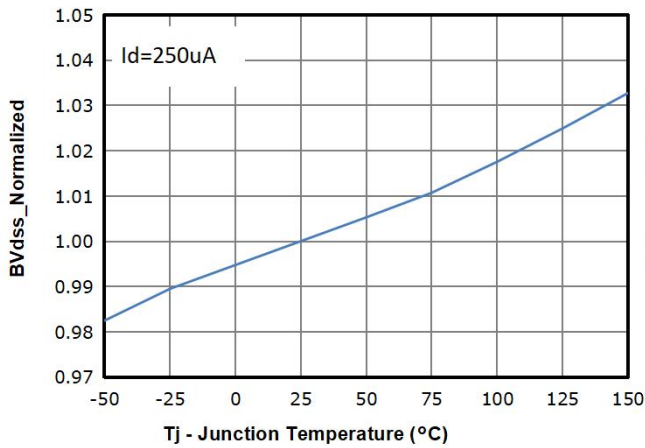


Fig 8: Capacitance Characteristics

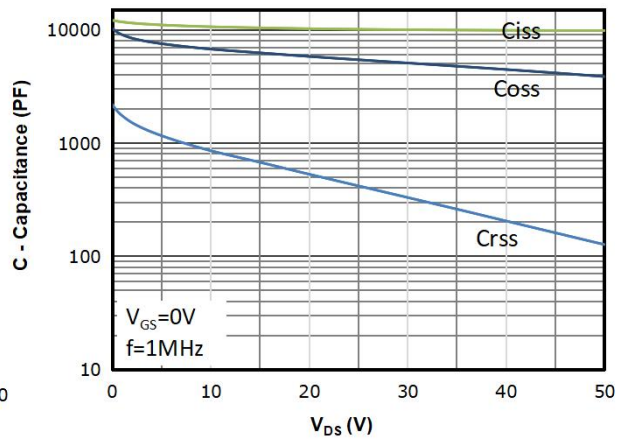


Fig 9: Gate Charge Characteristics

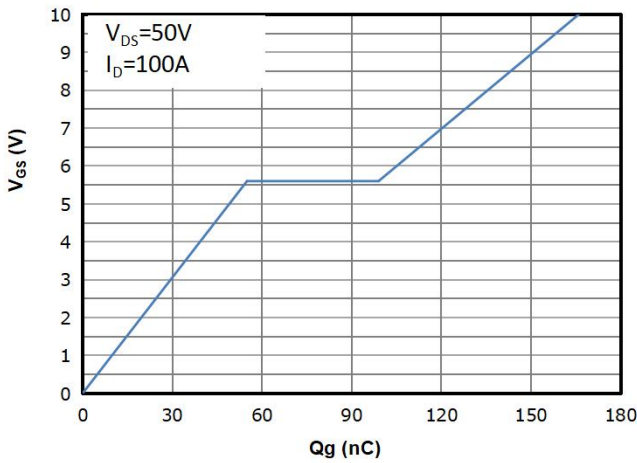


Fig 10: Body-diode Forward Characteristics

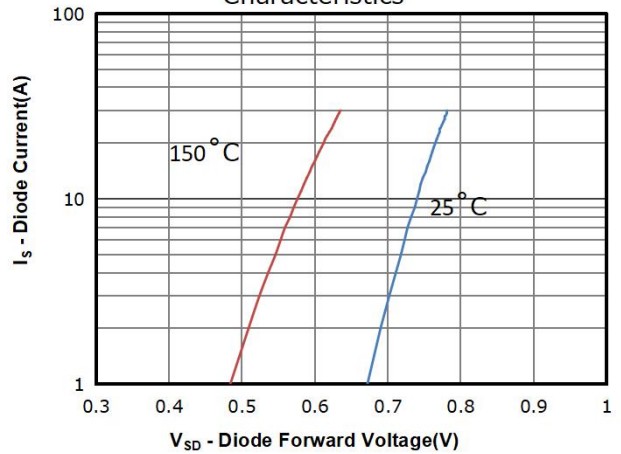


Fig 11: Power Dissipation

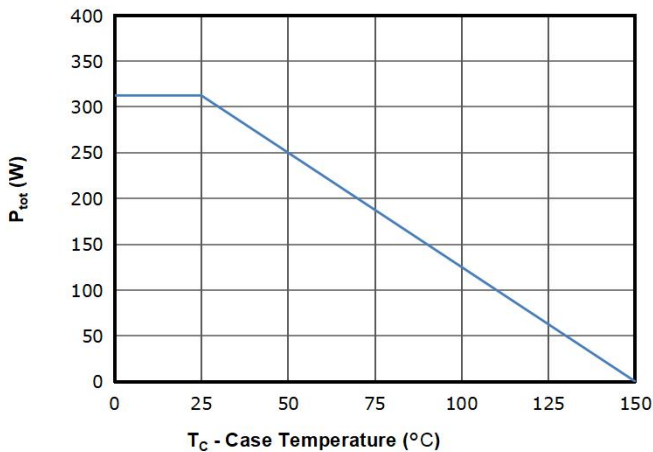


Fig 12: Drain Current Derating

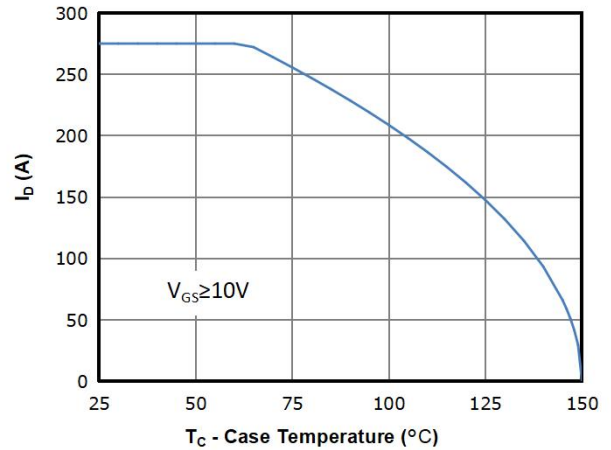




Fig 13: Safe Operating Area

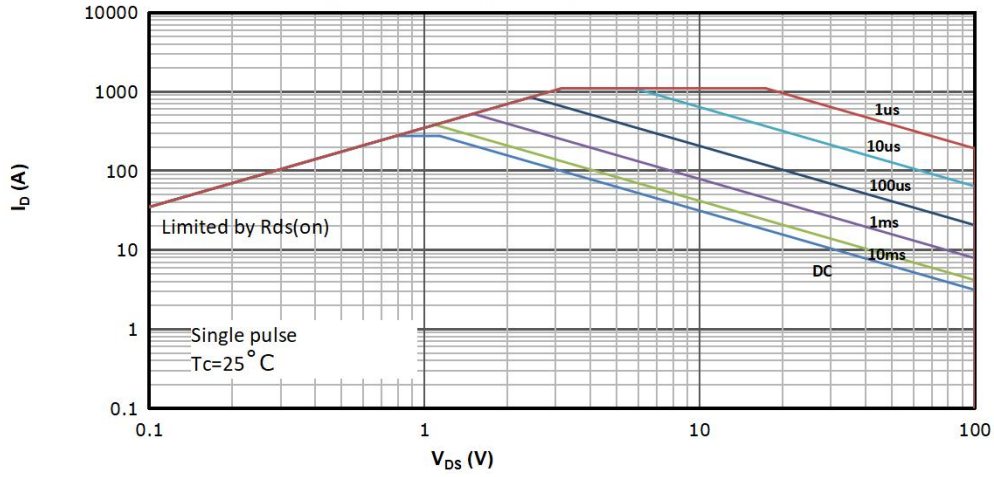
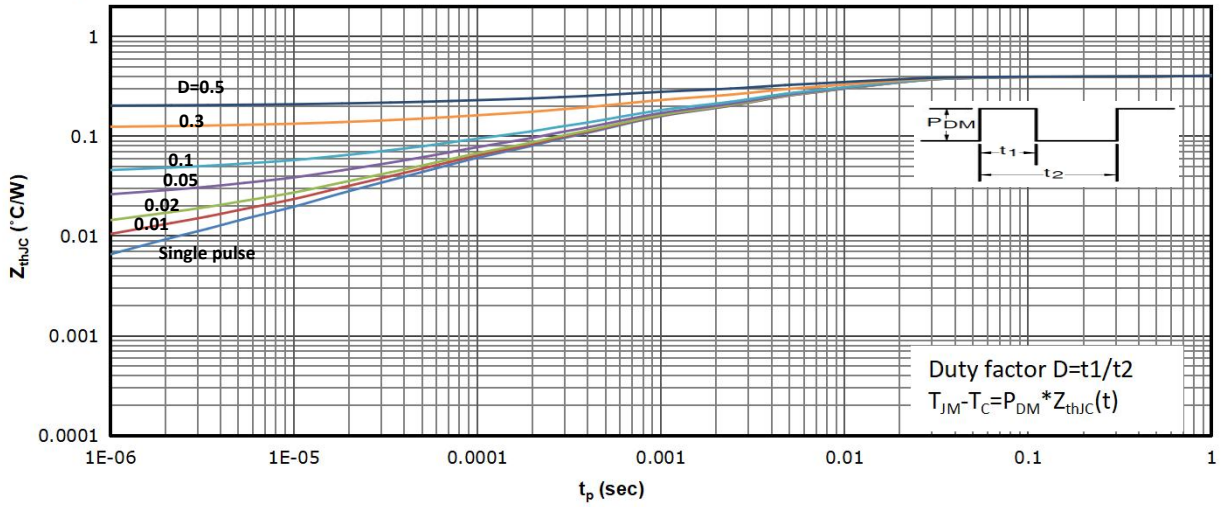


Fig 14: Max. Transient Thermal Impedance

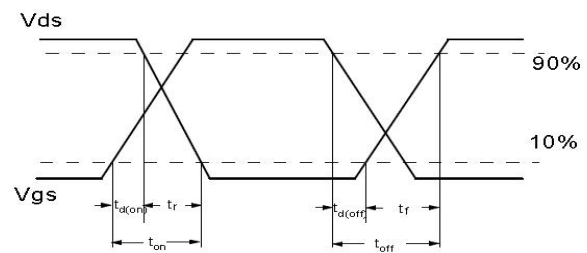


Test Circuit & Waveform

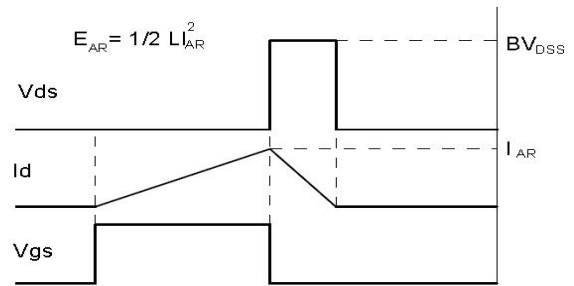
Gate Charge Test Circuit & Waveform



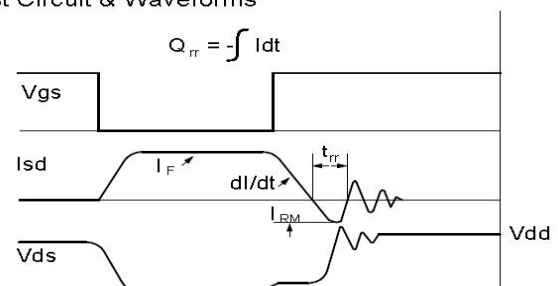
Resistive Switching Test Circuit & Waveforms



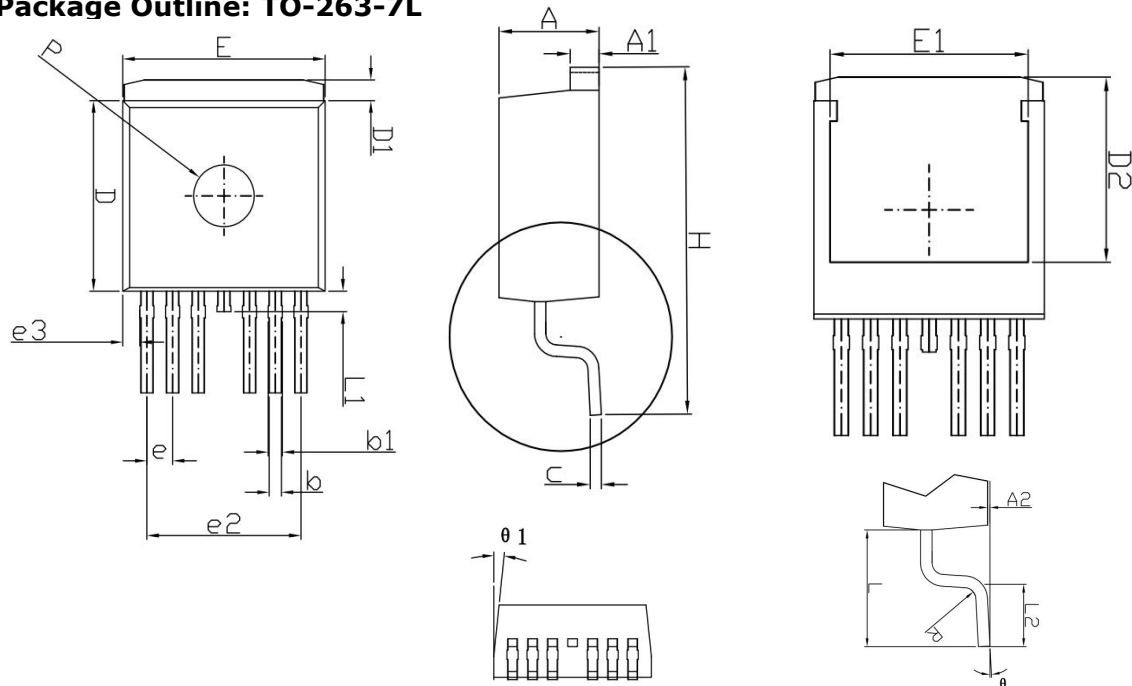
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: TO-263-7L



SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.70	0.169	0.185
A1	1.20	1.40	0.047	0.055
A2	0.05	0.30	0.002	0.012
b	0.50	0.70	0.020	0.028
b1	0.50	0.90	0.020	0.035
c	0.40	0.60	0.016	0.024
D	9.05	9.45	0.356	0.372
D1	0.70	1.30	0.028	0.051
D2	7.35	8.35	0.289	0.329
E	9.80	10.20	0.386	0.402
E1	8.10	9.10	0.319	0.358
e	1.07	1.47	0.042	0.058
e2	7.32	7.92	0.288	0.312
e3	0.64	1.04	0.025	0.041
H	14.65	15.65	0.577	0.616
L	4.47	5.47	0.176	0.215
L1	0.90	1.50	0.035	0.059
L2	2.20	2.80	7°	12°
θ	0°	8°	0°	8°
θ 1	0°	10°	0°	10°
φP	2.70	3.30	0.106	0.130



Revision History

Revision	Date	Major changes
1.0	2023/2/8	Release of Formal Version.

Disclaimer

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